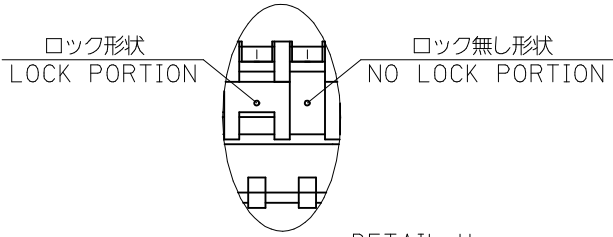
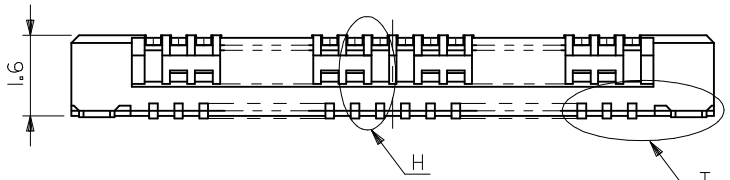
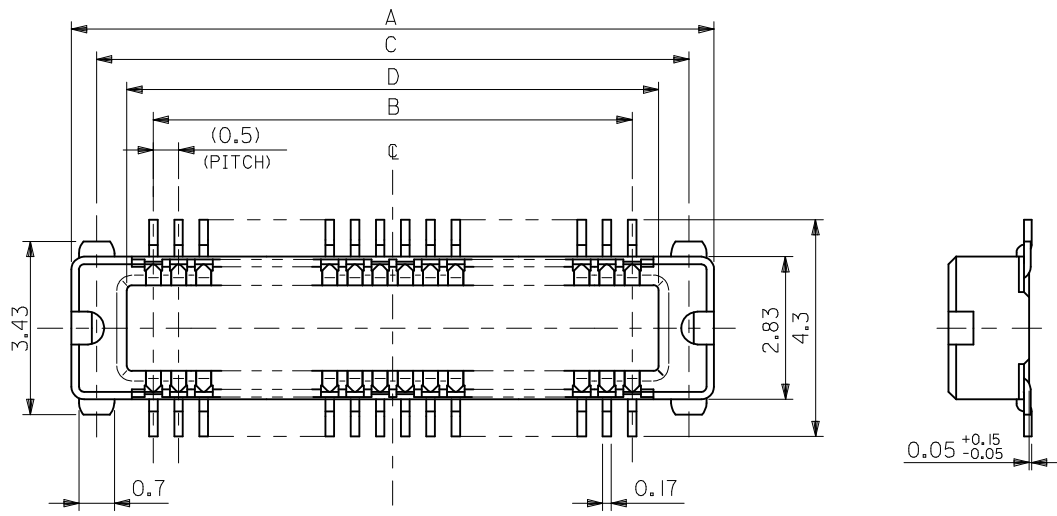


注記
NOTES:

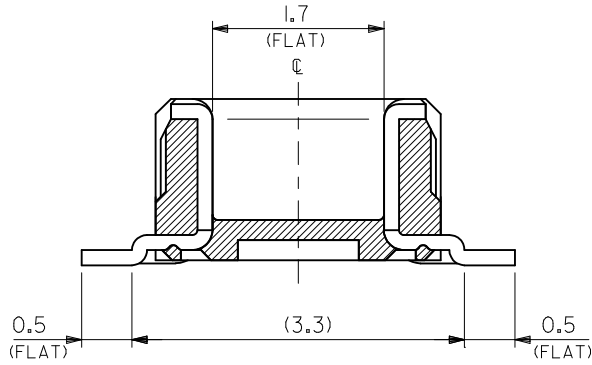
1. 材質
MATERIAL
ハウジング: LCP (液晶ポリマー)、ガラス充填、黒色、UL94V-0
HOUSING: LCP (LIQUID CRYSTAL POLYMER), GLASS FILLED, BLACK, UL94V-0
ターミナル: 銅合金 (t=0.15)
TERMINAL: COPPER ALLOY (t=0.15)
ネイル: 銅合金 (t=0.2)
NAIL: COPPER ALLOY (t=0.2)
2. メッキ仕様
PLATING
ターミナル
TERMINAL
接点部: 金メッキ 0.25マイクロメートル以上。
CONTACT AREA: GOLD 0.25 MICROMETER MINIMUM.
半田付け部: 金メッキ 0.4マイクロメートル以下。
SOLDER TAIL AREA: GOLD 0.4 MICROMETER MAXIMUM.
下地メッキ: ニッケルメッキ 1.5マイクロメートル以上。
UNDER PLATING: NICKEL 1.5 MICROMETER MINIMUM.
ネイル
NAIL
半田メッキ 3.0マイクロメートル以上。
Sn-Pb 3.0 MICROMETER MINIMUM.
下地メッキ: 銅メッキ 1.0マイクロメートル以上。
UNDER PLATING: CU 1.0 MICROMETER MINIMUM.
3. テール平坦度は、0.08ミリメートル以下。テールとネイルを併せた平坦度は、0.1ミリメートル以下。
TAIL COPLANARITY TO BE 0.08 MAXIMUM. TAILS AND NAILS COPLANARITY TO BE 0.1 MAXIMUM.
4. 嵌合相手: 54363-****
MATED CONN.: 54363-****



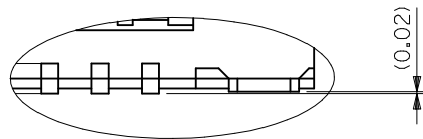
DETAIL H
SCALE 20

—#	30.55	31.75	29.5	32.75	55201-1208	55201-1201	120
12	13.05	14.25	12	15.25	55201-0508	55201-0501	50
20	10.55	11.75	9.5	12.75	55201-0408	55201-0401	40
30	8.05	9.25	7	10.25	55201-0308	55201-0301	30
20	5.55	6.75	4.5	7.75	55201-0208	55201-0201	20
□ック数 LOCKS	D	C	B	A	エンボス梱包品 EMBOSSED TAPE PACKAGING	製品番号 MATERIAL NO.	極数 CIRCUITS

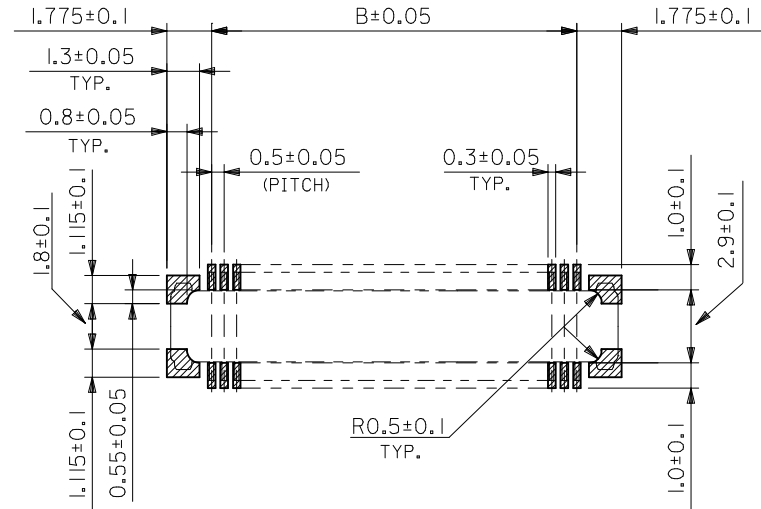
REVISED EC NO: J2009-0259 DRWN: YOSHIDAM 2008/08/07 CHKD: THARUYAMA 2008/08/07 APPR: NUKITA 2008/12/17	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY H. SHIMOMYAMA	DATE '98/06/24	TITLE 0.5 MM PITCH B/B CONN. PLUG HSG ASSY (H=2MM) EITH FITTING NAIL		
	10 OVER 30 UNDER	±0.25	CHECKED BY M. SASAO	DATE '98/06/24	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY H. IKESUGI	DATE '98/06/24	DOCUMENT NO. SD-55201-007	SHEET NO. 1 OF 2	
	ANGULAR ±3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE			
		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					



製品断面図 (半田付け部、吸着面寸法)
DETAIL FOR SOLDERING AND VACUUM AREA



T部陸詳細
DETAIL T



推奨基板寸法
RECOMMENDED PCB PATTERN LAYOUT
(SCALE:5-1)

REVISED EC NO: J2009-0259 DRWN: YOSHIDAM 2008/08/07 CHKD: THARUYAMA 2008/08/07 APPR: NUKITA 2008/12/17	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 20:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY H. SHIMOYAMA	DATE '98/06/24	TITLE 0.5 MM PITCH B/B CONN. PLUG HSG ASSY (H=2MM) WITH FITTING NAIL		
	10 OVER 30 UNDER	±0.25	CHECKED BY M. SASAO	DATE '98/06/24	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY H. IKESUGI	DATE '98/06/24	MATERIAL NO.	DOCUMENT NO.	SHEET NO.
	ANGULAR ±3 °		SEE TABLE		SD-55201-007		2 OF 2
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					